

IN THE SPECIFICATION:

Please amend paragraph number [0038] as follows:

[0038] In FIG. 8, a flexible dielectric film 20 is provided with a conductive film 30 (e.g., an 18  $\mu$ m thick copper film) laminated to a surface 22 thereof. Flexible dielectric film 20 may have dimensions that facilitate the fabrication of a plurality of strips 100 of multiple tape substrates 10 thereon (FIG. 14).

Please amend paragraph number [0059] as follows:

[0059] In FIG. 23, a strip 100 bearing a plurality of packaged semiconductor ~~device~~ devices 60 (only one shown for clarity) is positioned within a degator 110. More specifically, strip 100 is positioned beneath an upper degator 112, or the upper degator 112 is positioned over strip 100, with sprues 64 being received within corresponding slots 114 of upper degator 112. Strip 100 is also positioned beneath a lower degator 115, or lower degator 115 is positioned beneath strip 100, such that an extendable punch 116 is located beneath each mold gate 40 and sprue 64.